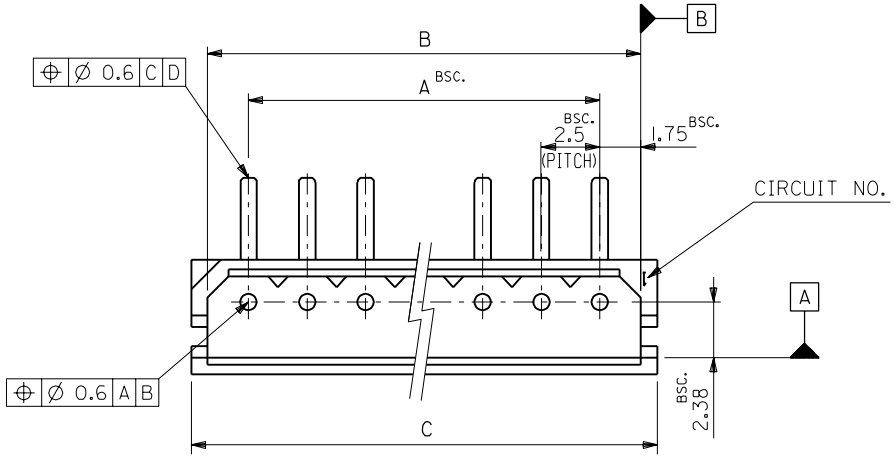
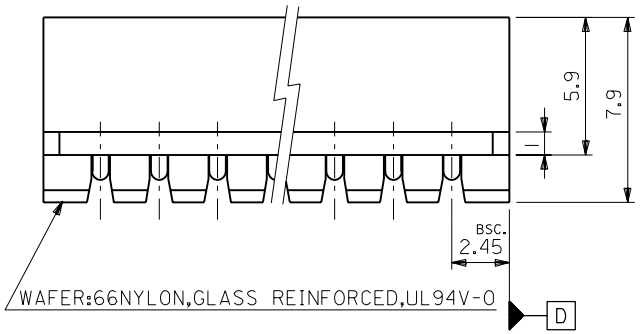
ENG. NO SD-5268-NA

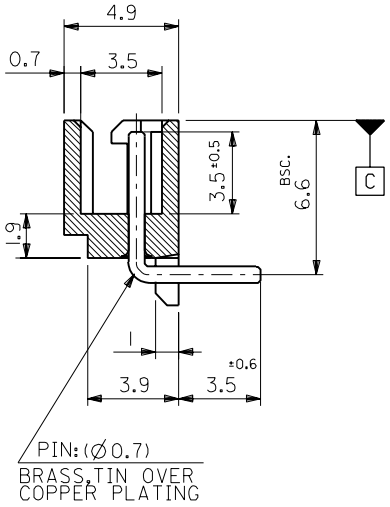
EDP NO. 22-05-7**5

:MM DIMENSIONS IN METRIC DO NOT SCALE DRAWING



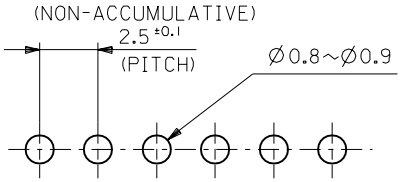
NOTE:
1.MATES WITH : 5264 SERIES.





C	B	A	EDP NO.	ENG.NO.	CKT.
52.4	51	47.5	22-05-7205	5268-20A	20
49.9	48.5	45	-7195	-19A	19
47.4	46	42.5	-7185	-18A	18
44.9	43.5	40	-7175	-17A	17
42.4	41	37.5	-7165	-16A	16
39.9	38.5	35	-7155	-15A	15
37.4	36	32.5	-7145	-14A	14
34.9	33.5	30	-7135	-13A	13
32.4	31	27.5	-7125	-12A	12
29.9	28.5	25	-7115	-11A	11
27.4	26	22.5	-7105	-10A	10
24.9	23.5	20	-7095	-09A	9
22.4	21	17.5	-7085	-08A	8
19.9	18.5	15	-7075	-07A	7
17.4	16	12.5	-7065	-06A	6
14.9	13.5	10	-7055	-05A	5
12.4	11	7.5	-7045	-04A	4
9.9	8.5	5	-7035	-03A	3
7.4	6	2.5	22-05-7025	5268-02A	2

(NON-ACCUMULATIVE)



RECOMMENDED P.C. BOARD HOLE DIM.(t=1.6)

角度 ANGLE	±3°
30 以上 OVER	±0.3
10 以上 OVER 30 未満 UNDER	±0.25
10 未満 UNDER	±0.2
一般公差 GENERAL TOLERANCES	

記号 LTR	変更内容 REVISION RECORD	DR. / CHK.	日付 DATE
C	REVISED & REDRAWN (JI059IN)	K.T / H.H	'91/11/5

REVISE ONLY ON CAD SYSTEM

材料 MATERIAL	〃
仕上げ FINISH	〃
適用電線範囲 WIRE RANGE	〃
被覆外径 INS. RANGE	〃
DRAWN BY K.TOJO '91/11/5	CHK'D BY '92/08/31 H.H
APP'D BY '92/08/31 M.ENOMOTO	尺度 SCALE 5-1

molex MOLEX-JAPAN CO.,LTD. 日本モレックス株式会社

EDP. NO. 22-05-7**5

ENG. NO. SD-5268-NA REV C

TITLE 名称 2.5 LOW PROFILE WAFER ASS'Y 90° BEND

5268.S60 A

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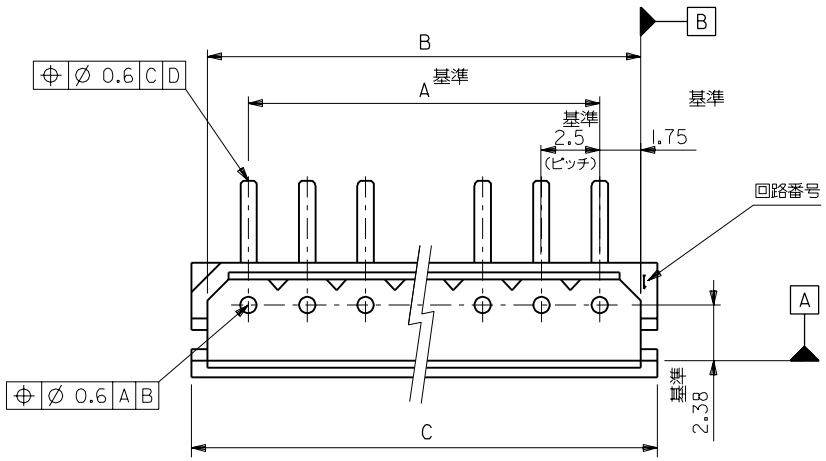
MXJ-8

ENG. NO SD-5268-NA

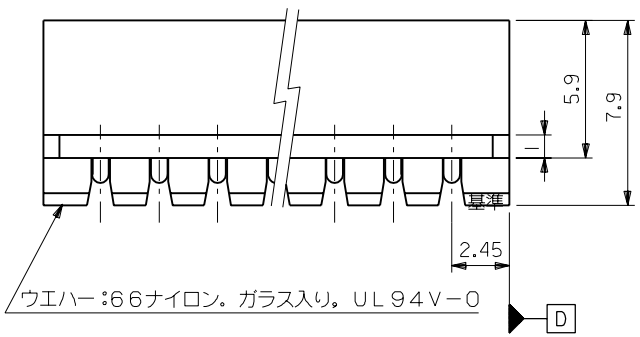
EDP NO. 22-05-7**5

:MM DIMENSIONS IN METRIC DO NOT SCALE DRAWING

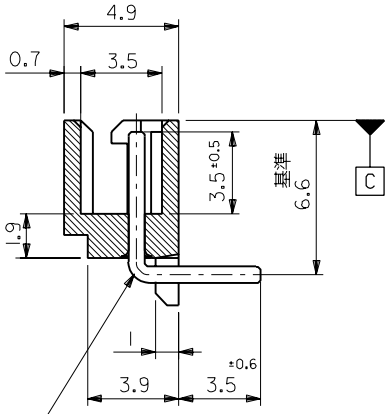


NOTE:

1. 嵌合相手：5264 シリーズ



ウエハー：66ナイロン，ガラス入り，UL94V-0



ピン：(Ø0.7)
黄銅，銅下地錫メッキ

39.9	38.5	35	22-05-7155	5268-15A	15
37.4	36	32.5	-7145	-14A	14
34.9	33.5	30	-7135	-13A	13
32.4	31	27.5	-7125	-12A	12
29.9	28.5	25	-7115	-11A	11
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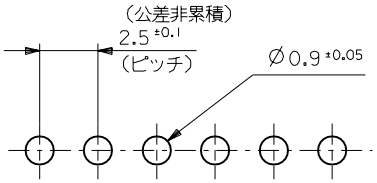
12.4	11	7.5	-7045	-04A	4
9.9	8.5	5	-7035	-03A	3
7.4	6	2.5	22-05-7025	5268-02A	2
C	B	A	EDP NO.	ENG.NO.	極数



基板取付穴推奨寸法（t=1.6）

角度 ANGLE	±3°
30 以上 OVER	±0.3
10 以上 OVER 30 未満 UNDER	±0.25
10 未満 UNDER	±0.2
一般公差 GENERAL TOLERANCES	

記号 LTR	変更内容 REVISION RECORD	DR.	CHK.	日付 DATE
C	再作図及び変更(JI0590)	K.T	H.H	'91/7/26

REVISE ONLY ON CAD SYSTEM

材料 MATERIAL —〃—

仕上げ FINISH —〃—

適用電線範囲 WIRE RANGE —〃—

被覆外径 INS. RANGE —〃—

DRAWN BY K.TOJO '91/7/26

CHK'D BY '92/08/31 H.H

APP'D BY '92/08/31 M.ENOMOTO

尺度 SCALE 5-1

MOLEX-JAPAN CO.,LTD. 日本モレックス株式会社

EDP. NO. 22-05-7**5

ENG. NO. SD-5268-NA

REV C

TITLE 名称 2.5 LOW PROFILE WAFER ASS'Y 90° BEND

5268.S30 A

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